

Amendments to the Claims:

Claim 1 has been amended herein. New claims 4 and 5 are presented herein. Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Currently Amended) A semiconductor die, comprising:
a rectangular body having an active surface and a longitudinal centerline; and
a plurality of bond pads disposed adjacent the longitudinal centerline, wherein the plurality of bond pads are arranged in at least one longitudinal row comprising at least two longitudinally adjacent groups of bond pads, each bond pad within a group of bond pads being longitudinally separated from adjacent bond pads within the group of bond pads by an interpad spacing of less than about 0.5 mm, each group of bond pads being separated from longitudinally adjacent groups of bond pads by an intergroup spacing of greater than about 0.5 mm ~~greater space than a space between bond pads within a group.~~
2. (Original) The semiconductor die of claim 1, wherein the at least two longitudinally adjacent groups of bond pads consists of two longitudinally adjacent groups.
3. (Original) The semiconductor die of claim 1, wherein the at least one longitudinal row comprises two longitudinal rows flanking the longitudinal centerline.
4. (New) The semiconductor die of claim 1, wherein the intergroup spacing is about 1.5 times the interpad spacing.
5. (New) The semiconductor die of claim 4, wherein the interpad spacing is about 0.4 mm and the intergroup spacing is about 0.6 mm.